



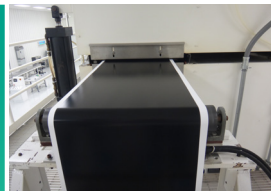
P-SHIELD® EMI Shielding & Grounding Materials



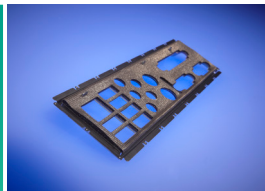
P-SHIELD® EMI shielding materials are used to provide an electrically conductive seal for electronic device openings and housing covers to prevent or restrict electromagnetic interference. We offer fabric tapes, film tapes, foil tapes, foam tapes, and conductive adhesives. Polymer Science's P-SHIELD® EMI shielding and grounding materials are the perfect solution for today's evolving electronic device market.



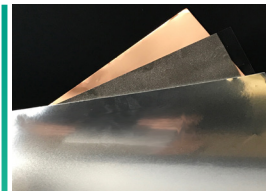
P-SHIELD® fabric tapes have thin, lightweight profiles and durable elements, making them perfect solutions for today's ever-shrinking electronics housing designs.



P-SHIELD® film tapes are thin, flexible and durable while maintaining their highly conductive properties.



P-SHIELD® foam tapes are conformable and compressible. They are thin, lightweight materials with excellent EMI shielding and grounding properties.



P-SHIELD® foil tapes are made of aluminum and copper laminated with conductive acrylic pressure sensitive adhesive providing reliable EMI shielding and grounding solutions.



P-SHIELD® electrically conductive transfer adhesives offer effective bonding solutions for electronic device designs that require EMI shielding and grounding.

Markets Served



- Consumer Electronics
- Aerospace
- Automotive Components
- Electric Vehicle
- Telecommunications
- Consumer IoT
- Business IoT

Polymer Science provides pressure sensitive adhesives (PSAs) and coated materials to meet the complex needs of electronic component designs. Our diverse offering of materials provide solutions to many bonding applications that increase reliability and decrease production costs.

Our team of highly skilled engineers and technical staff, in conjunction with our state-of-the-art equipment, provide you with a quality product that is consistent with your application requirements.

Our design team works quickly to provide the solutions you need, allowing your project to expeditiously move from conception to commercialization giving you the edge to ensure your next project is a success.

Characteristics of P-SHIELD® EMI Shielding and Grounding Materials

Fabric Tapes



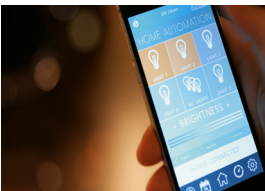
- Conductive Copper Nickel Plated Fabrics
- Fabrics Include Woven, Nonwoven and Durable Ripstop
- Heat Activated Adhesive Options Available
- Materials Effectively Shield Over a Wide Frequency Range
- Fabrics are Laminated with Conductive Acrylic Pressure Sensitive Adhesive
- Ultra-Thin Strong Materials are Flexible and Contour Around Tight Angles and Irregular Surfaces

Film Tapes



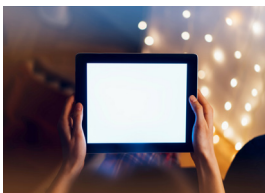
- Static Dissipative
- High Chemical Resistance
- Polyimide Films Available for High Temperature Applications
- Electrically Insulating Options
- Anisotropic & Isotropic Options
- Black Film and Black Adhesive Offer Advanced Light Blocking Properties

Foam Tapes



- Polyurethane, Polyolefin and Silicone Foams
- Components Available for Fabric Over Foam Gasket Materials
- Robust Material Constructions are Durable and Ideal for Converting
- Copper and Nickel Plated Foams and Conductive PSAs Result in High Conductivity in the x, y and z axes.

Foil Tapes



- Copper and Aluminum Foils
- Laminated with Conductive Acrylic Pressure Sensitive Adhesive
- Highly Conductive
- Fabric/Foil Composite Offered for Increased Durability
- Offer superior EMI protection
- Economical
- Thin Foil Tapes will Contour around Tight Angles and Irregular Surfaces

Conductive Adhesives



- Excellent x, y and z-Axis Conductivity
- Easily Converted
- Low VOC
- PSA and Heat Activated Options Available
- Good Shear Strength